

## SILICON CONTROLLED RECTIFIERS

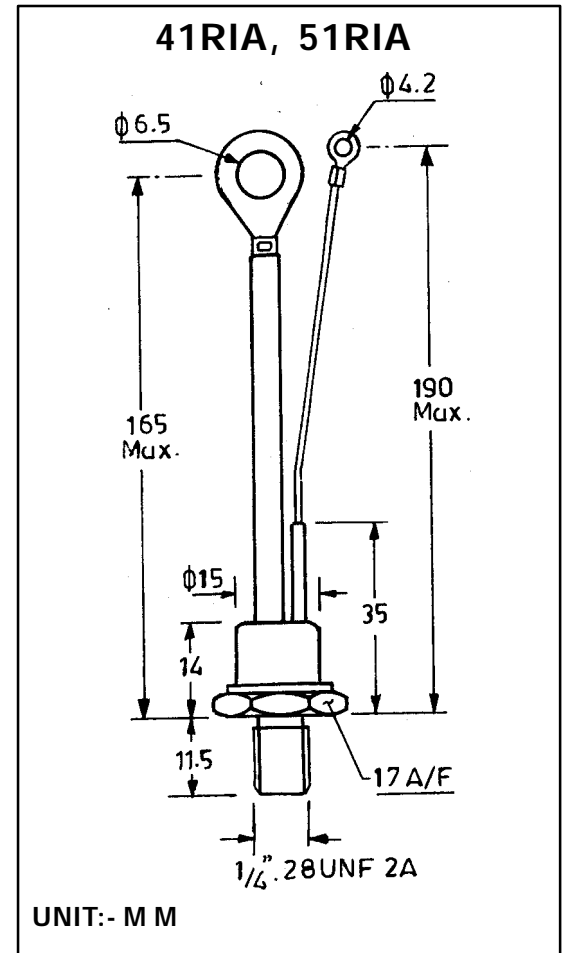
### 41RIA, 51RIA SERIES Power Silicon Controlled Rectifiers 64, 80 Amp RMS SCRs Types : 41RIA10-41RIA140, 51RIA10-51RIA140

#### FEATURES

- ❖ All diffused series.
- ❖ High di/dt and dv/dt capabilities.
- ❖ Reliable blocking at elevated temperature.
- ❖ High surge current rating.
- ❖ High I<sup>2</sup>t capability.
- ❖ Excellent dynamic characteristics.

#### THERMAL MECHANICAL SPECIFICATIONS

R <sub>thjc</sub>	Maximum thermal resistance junction-to-case	41RIA	51RIA
		0.4°C/W	0.35°C/W
R <sub>thcs</sub>	Contact thermal resistance case-to-sink	0.25°C/W	
T <sub>J</sub>	Junction operating temp. range	-65°C to +125°C	
T <sub>stg</sub>	Storage temperature range	-65°C to +150°C	
	Mounting torque (Non-lubricated threads)	0.4 M-Kg min. 0.6 M-Kg max.	
	Approximate weight	30 gms.	



#### ELECTRICAL RATINGS

TYPE	41RIA / 51RIA	10	20	40	60	80	100	120	140
V <sub>DRM</sub>	Max. repetitive peak off state voltage (V)	100	200	400	600	800	1000	1200	1400
V <sub>RRM</sub>	Max. repetitive peak reverse voltage (V)	100	200	400	600	800	1000	1200	1400
V <sub>RSM</sub>	Max. non-repetitive peak reverse voltage (V)	150	300	500	700	900	1100	1300	1500
I <sub>RM</sub> & I <sub>DM</sub>	Max. peak reverse & off state current @ rated V <sub>DRM</sub> & V <sub>RRM</sub> 125°C -mA	20	15	15	15	15	15	15	15

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## 41 RIA, 51 RIA SERIES

### ELECTRICAL SPECIFICATIONS

	ON-STATE	41RIA	51RIA	Units	Conditions	
$I_{T(RMS)}$	Max. RMS on-state current	65	80	A		
$I_{T(AV)}$	Max. average on-state current	40	50	A	$T_C = 94^\circ\text{C max.}, 180^\circ\text{C sinusoidal conduction.}$	
$I_{TSM}$	Max. peak one cycle non-repetitive surge current	1050	1200	A	50 Hz half cycle sine wave or 6 ms rectangular pulse.	Following any rated load conditions and with rated $V_{RRM}$ applied following surge.
		1250	1430			Following any rated load condition and with no voltage reapplied following surge.
$I^2t$	Max. $I^2t$ capability for fusing	5700	7200	$A^2s$	$t = 10 \text{ ms}$ Rated $V_{RRM}$ applied following surge, initial $T_J = 125^\circ\text{C}$	
$I^2t$	Max. $I^2t$ capability for individual device fusing (1)	8060	10180	$A^2s$	$t = 10 \text{ ms}$ $V_{RRM}$ following surge = 0, initial $T_J = 125^\circ\text{C}$	
$I^2t$	Max. $I^2t$ capability for individual device fusing	80600	101800	$A^2s$	$t = 0.1 \text{ to } 10 \text{ ms}$ $V_{RRM}$ following surge = 0,, initial $T_J = 125^\circ\text{C}$	
$V_{TM}$	Max. peak on-state voltage	1.65	1.6	V	$T_J = 25^\circ\text{C}, I_{TM} = \pi \times I_{T(AV)}$	
$I_H$	Max. holding current	200		mA	$T_J = 25^\circ\text{C}, \text{anode supply} = 22\text{V}, \text{initial } I_T = 2.0\text{A}$	
$I_L$	Max. latching current	400		mA	Anode supply = 6V, resistive load.	

### BLOCKING

(1)  $I^2t$  for time  $t_x = I^2t \times t_x$

$dv/dt$	Min. critical rate-of-rise of off-state voltage	200	$V/\mu\text{s}$	$T_J = 125^\circ\text{C}$ . Exponential to 100% rated $V_{DRM}$	Zero gate bias voltage gate open circuited.
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### SWITCHING

#### 41 / 51 RIA

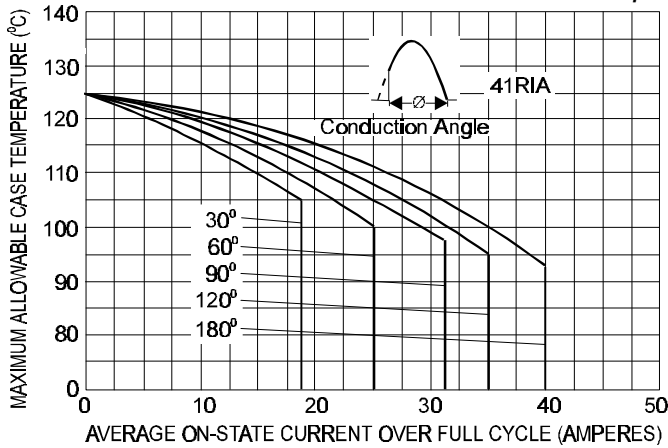
$t_d$	Typical delay time	0.9	$\mu\text{s}$	$T_C = 25^\circ\text{C}, V_{DM} = \text{rated } V_{DRM}, I_{TM} = 10\text{A}$ dc resistive circuit, Gate pulse 10V, $15\Omega$ source $t_p = 20 \mu\text{s}$
$di/dt$	Max non-repetitive rate of rise of turned-on current $V_{RRM} = \text{upto } 1400 \text{ V}$	100	$A/\mu\text{s}$	$T_C = 125^\circ\text{C}, V_{DM} = \text{rated } V_{DRM}, I_{TM} = 2 \times \text{rated } di/dt$ . Gate pulse 20V, $15\Omega$ , $t_p = 6 \mu\text{s}, t_r = 0.1 \mu\text{s}$ max.
$t_q$	Typical turn-off time	110	$\mu\text{s}$	$T_C = 125^\circ\text{C}, I_{TM} = 50\text{A}, di/dt = 10 \text{ A}/\mu\text{s}, V_R$ during turn-off interval = 50 V min., reapplied $dv/dt = 20 \text{ V}/\mu\text{s}$ linear to rated $V_{DRM}$ Gate bias : 0V, $100\Omega$

### TRIGGERING

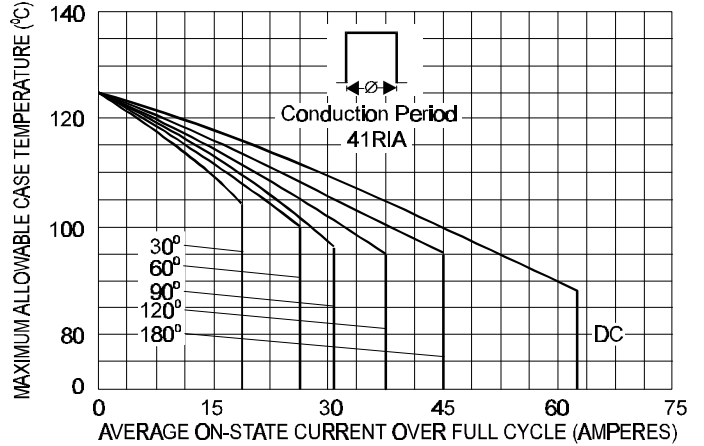
$P_{GM}$	Max. peak gate power	10	W	$t_p \leq 5\text{ms}$	
$P_{G(AV)}$	Max. average gate power	2.5	W		
$I_{GM}$	Max. peak positive gate current	2.5	A		
$+V_{GM}$	Max. peak positive gate voltage	20	V		
$-V_{GM}$	Max. peak negative gate voltage	10	V		
$I_{GT}$	Max. required DC gate current to trigger	250	mA	$T_J = -40^\circ\text{C}$	Max. required gate trigger current is the lowest value which will trigger all units with + 6V anode-to-cathode.
		100		$T_J = 25^\circ\text{C}$	
		50		$T_J = 125^\circ\text{C}$	
$V_{GT}$	Max. required DC gate voltage to trigger	3.5	V	$T_J = -40^\circ\text{C}$	Max. required gate trigger voltage is the lowest value which will trigger all units with + 6V anode-to-cathode.
		2.5		$T_J = 25^\circ\text{C}$	
$V_{GD}$	Max. DC gate voltage not to trigger	0.2	V	$T_J = 125^\circ\text{C}$	Max. gate current or voltage not to trigger is the maximum value which will not trigger any unit with rated $V_{DRM}$ anode-to-cathode.
$I_{GD}$	Max. DC gate current not to trigger	5.0	mA	$T_J = 125^\circ\text{C}$ $V_{DRM} = \text{rated voltage}$	

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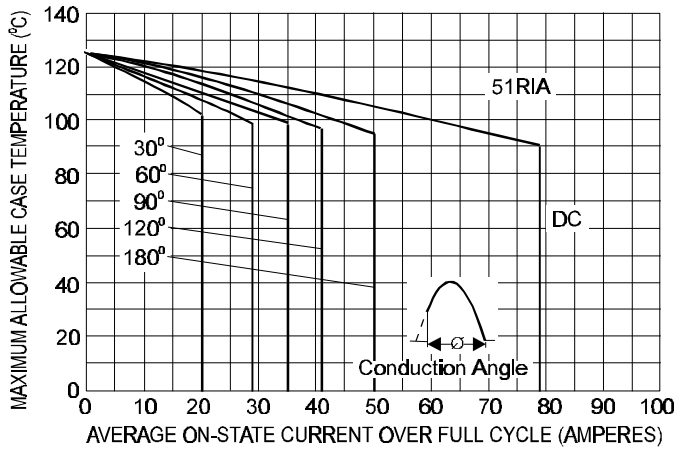
## 41 RIA, 51 RIA SERIES



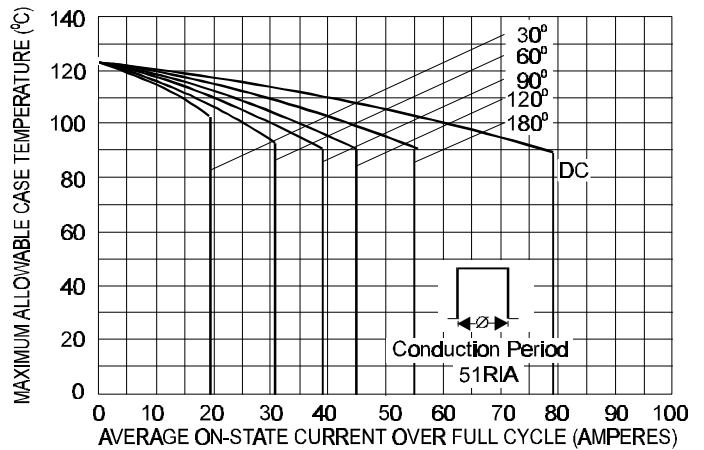
**Fig. 1 - On-state Current Vs. Case Temperature (Sinusoidal Current Waveform, 50 to 400 Hz)**



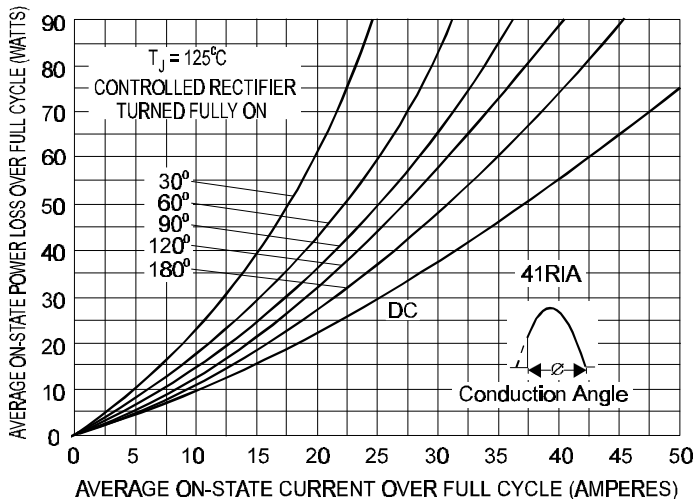
**Fig. 2 - On-state Current Vs. Case Temperature (Rectangular Current Waveform, 50 to 400 Hz)**



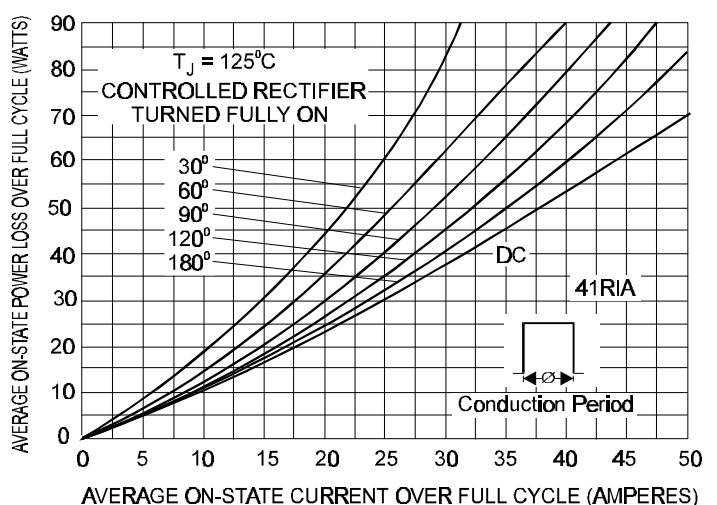
**Fig. 3 - On-state Current Vs. Case Temperature (Sinusoidal Current Waveform, 50 to 400 Hz)**



**Fig. 4 - On-state Current Vs. Case Temperature (Rectangular Current Waveform, 50 to 400 Hz)**



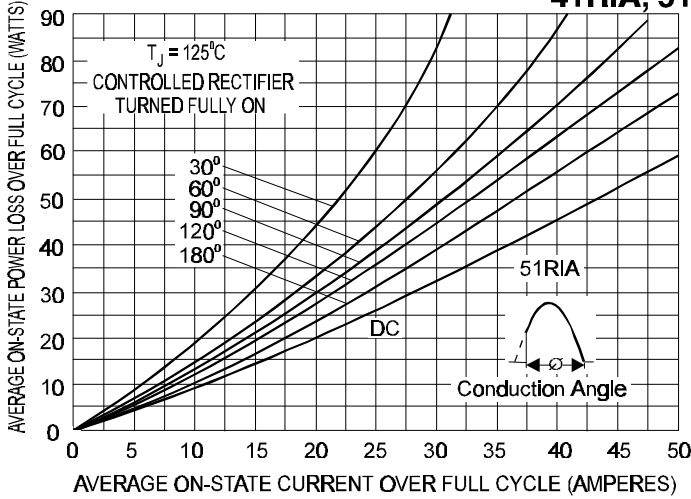
**Fig. 5 - Maximum Low-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)**



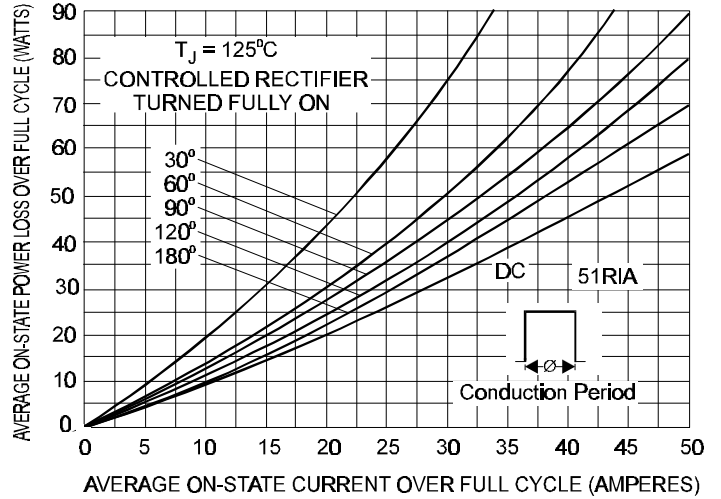
**Fig. 6 - Maximum Low-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)**

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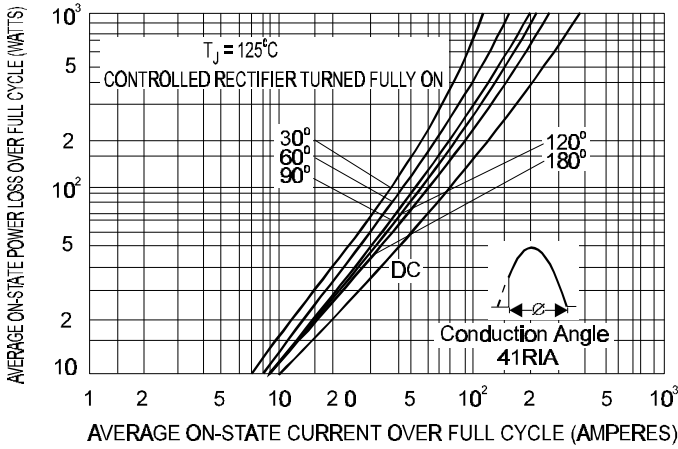
## 41RIA, 51RIA SERIES



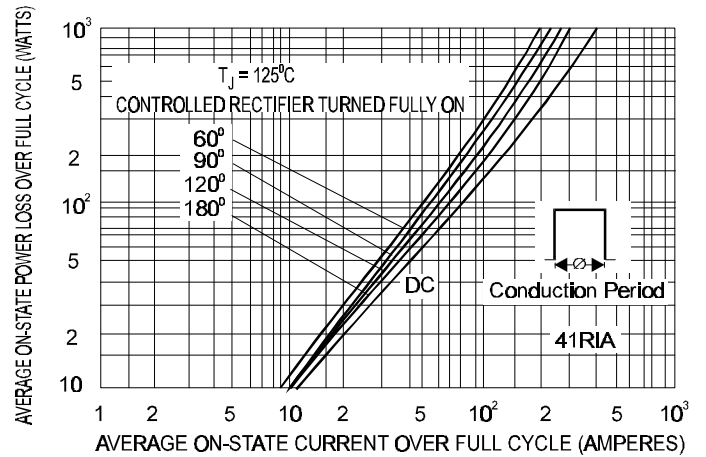
**Fig. 7 - Maximum Low-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)**



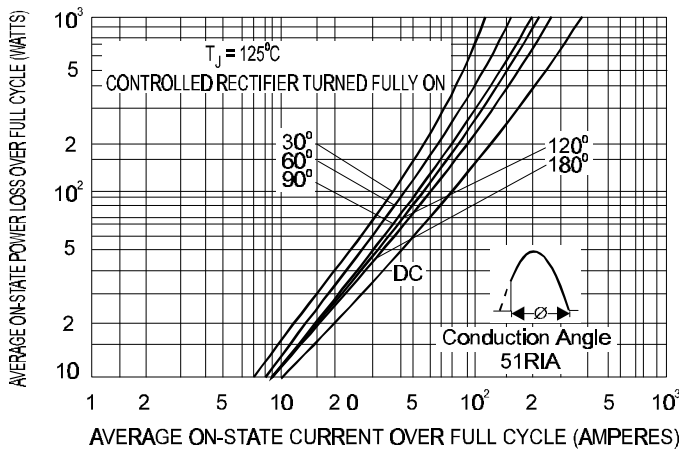
**Fig. 8 - Maximum Low-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)**



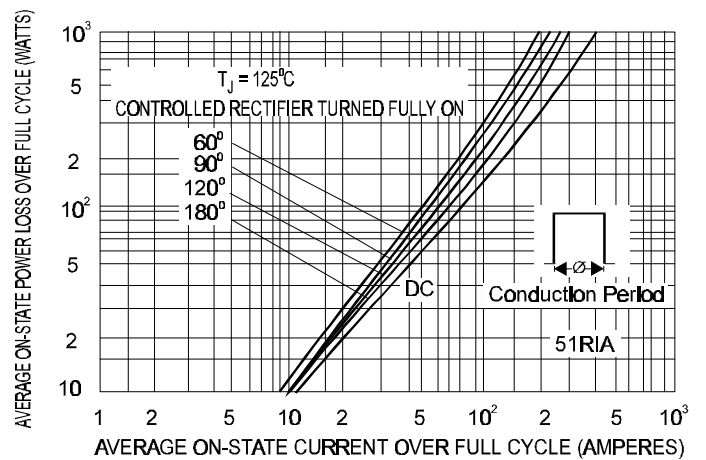
**Fig. 9 - Maximum High-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)**



**Fig. 10 - Maximum High-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)**



**Fig. 11 - Maximum High-Level On-state Power Loss Vs. Current (Sinusoidal Current Waveform)**



**Fig. 12 - Maximum High-Level On-state Power Loss Vs. Current (Rectangular Current Waveform)**

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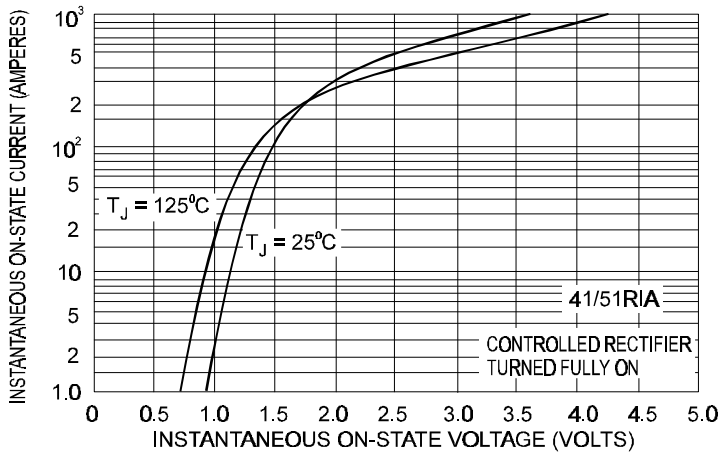


Fig. 13 - Maximum On-state Voltage Vs. Current

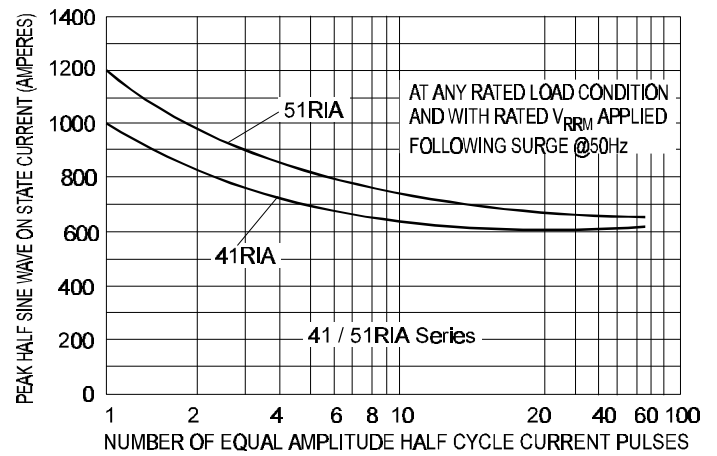


Fig. 14 - Maximum Non-Repetitive Surge Current Vs. Number of Current Pulses

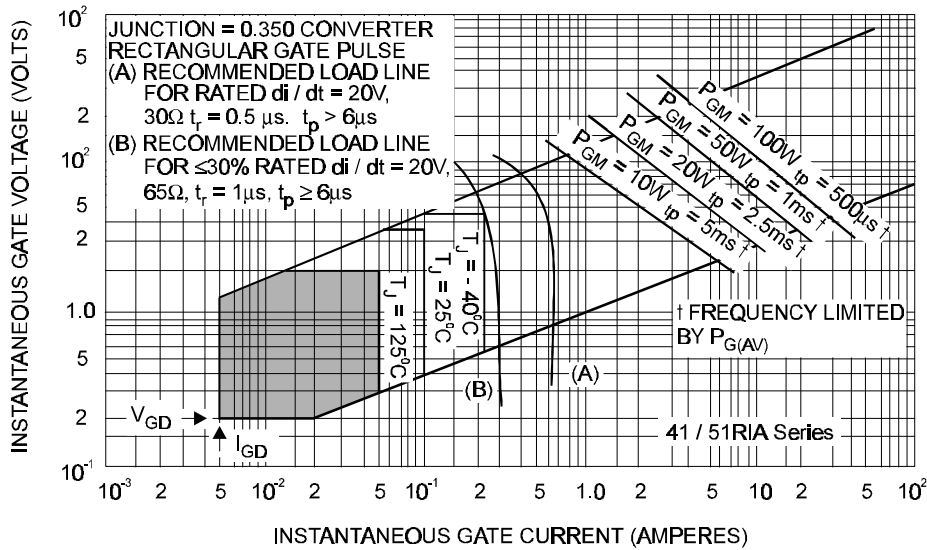


Fig. 15 - Gate Characteristics

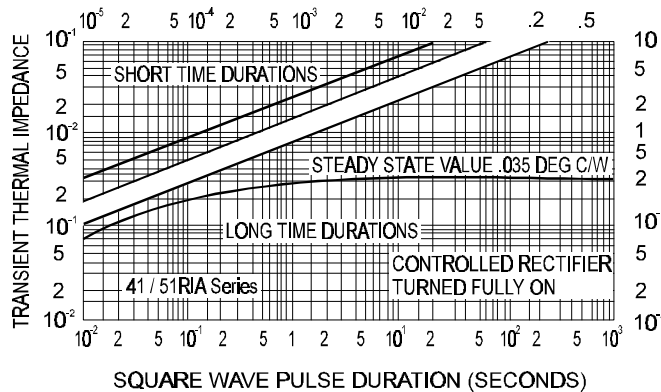


Fig. 16 - Maximum Transient Thermal Impedance, Junction To Case Vs Square Wave Pulse Duration